



Material Content Data Sheet



Sales Product Name		BSD816SN H6327		Issued		1. August 2018		
MA#		MA000974362						
Package		PG-SOT363-6-6		Weight*		6.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		311	
	noble metal	gold	7440-57-5	0.008	0.12		1204	
	inorganic material	silicon	7440-21-3	0.122	1.84	1.99	18367	19882
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		494	
	non noble metal	chromium	7440-47-3	0.010	0.15		1482	
	non noble metal	copper	7440-50-8	3.275	49.16	49.37	491802	493877
wire	non noble metal	copper	7440-50-8	0.050	0.76	0.76	7568	7568
encapsulation	organic material	carbon black	1333-86-4	0.029	0.44		4352	
	plastics	epoxy resin	-	0.623	9.36		93563	
	inorganic material	silicondioxide	60676-86-0	2.246	33.73	43.53	337262	435177
leadfinish	non noble metal	tin	7440-31-5	0.213	3.20	3.20	32016	32016
plating	noble metal	silver	7440-22-4	0.076	1.15	1.15	11480	11480
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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